HIGH TEMPERATURE ELECTRONICS, COMMUNICATIONS, AND SUPPORTING TECHNOLOGIES FOR VENUS MISSIONS

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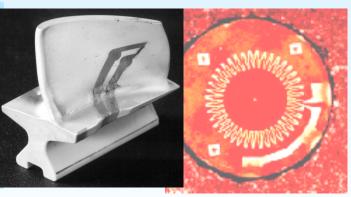
L. Y. Chen

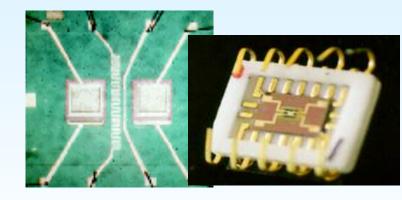
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SENSORS AND ELECTRONICS TECHNOLOGY BRANCH SCOPE OF WORK

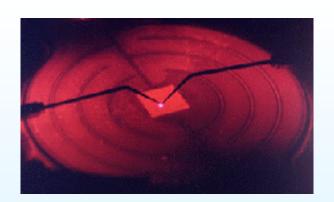




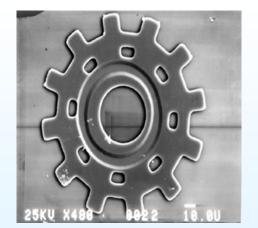


PHYSICAL SENSORS (T, Strain, Heat Flux)

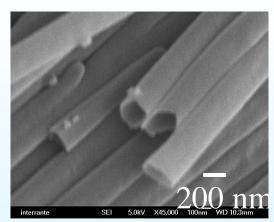
CHEMICAL SENSORS



SILICON CARBIDE HIGH TEMP ELECTRONICS



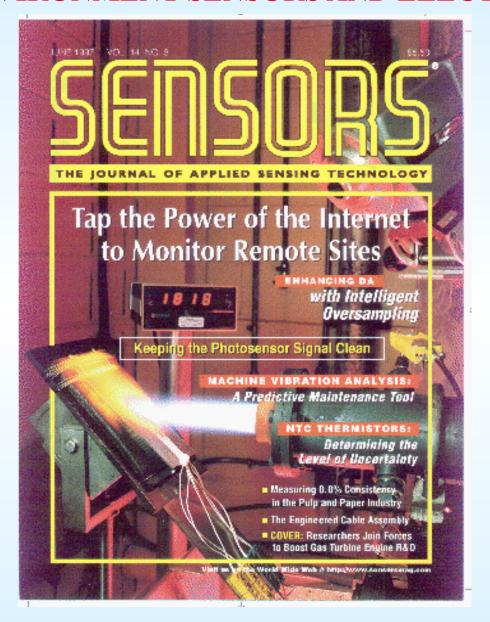
MICRO-ELECTRO-MECHANICAL SYSTEMS



NANOTECHNOLOGY



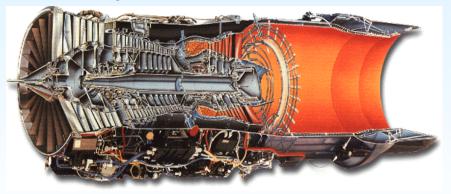
NASA GRC: CUTTING EDGE DEVELOPMENT HARSH ENVIRONMENT SENSORS AND ELECTRONICS



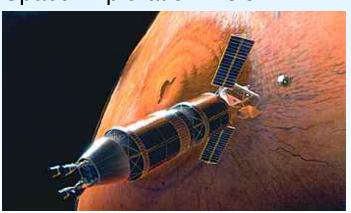


HIGH TEMPERATURE ELECTRONICS AND SENSORS BENEFITS TO NASA MISSIONS

Intelligent Propulsion Systems



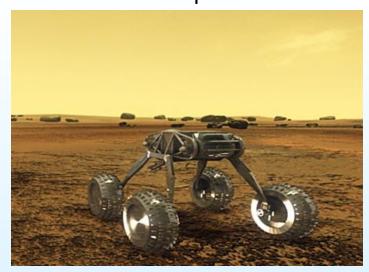
Space Exploration Vision PMAD



More Electric + Distributed Control Aircraft



Venus Exploration





HARSH ENVIRONMENT VENUS MISSION REQUIREMENTS

- SURFACE CONDITIONS
 - > TEMPERATURE: 450-500 C
 - > PRESSURE: 90 bar PREDOMINATELY (~100 TIMES EARTH)
 - > SULFURIC ACID PARTICLES IN CLOUD DECK
 - > 96.5% CO2 and 3.5% N2; Trace Gases include H2O, SO2, CO, HCL, H2, and HF
- SOME PARAMETERS OF INTEREST: TEMPERATURE, PRESSURE, CHEMICAL SPECIES, FLOW (WIND)
- TEMPERATURE CONTROL INCREASES SYSTEM COMPLEXITY/RISK TO MISSION
- NEED TO SHIELD SYSTEM FROM EXTREME ENVIRONMENTS YIELDS INCREASE IN SIZE AND WEIGHT
- LIMITED INFORMATION AVAILABLE FROM IN-SITU SYSTEMS DUE TO HARSH ENVIRONMENTS INVOLVED
- SCIENTIFIC COMMUNITY: LACK OF VIABLE HARSH SENSOR SYSTEMS SENSORS AND ELECTRONICS FOR IN-SITU CHARACTERIZATION
- IN SOME AREAS, NASA GRC HAS ALREADY TECHNOLOGY SOLUTIONS ISSUES NEEDED BY SMD FOR HARSH ENVIRONMENT APPLICATIONS



HARSH ENVIRONMENT ELECTRONICS AND SENSORS APPLICATIONS

• NEEDS:

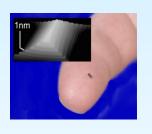
- > OPERATION IN HARSH ENVIRONMENTS
- > RANGE OF PHYSICAL AND CHEMICAL MEASUREMENTS
- > INCREASE DURABILITY, DECREASE THERMAL SHIELDING, IMPROVE IN-SITU OPERATION
- RESPONSE: UNIQUE RANGE OF HARSH ENVIRONMENT TECHNOLOGY AND CAPABILITIES
 - > STANDARD 500C OPERATION BY MULTIPLE SYSTEMS
 - > TEMPERATURE, PRESSURE, CHEMICAL SPECIES, WIND AVAILABLE
 - > HIGH TEMPERATURE ELECTRONICS TO MAKE SMART SYSTEMS



1998 R&D 100 Award



1995 R&D 100 Award



2004 R&D 100 Award



991 R&D 100 Award

- ALL-IN-ONE SHOP FOR HARSH ENVIRONMENT SYSTEM APPLICATIONS
- ENABLE EXPANDED MISSION PARAMETERS/IN-SITU MEASUREMENTS

Range of Physical and Chemical Sensors for Harsh Environments



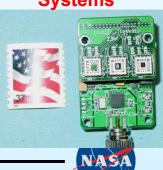
Harsh Environment
Packaging
(2000 hours at 500C)



High Temperature Signal Processing and Wireless

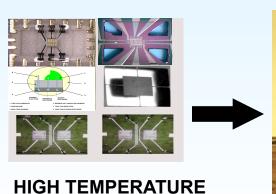


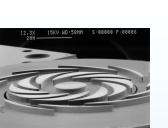
Long Term: High Temperature "Lick and Stick" Systems



VENUS SCIENTIFIC MISSIONS LIMITED BY AVAILABILITY OF HARSH **ENVIRONMENT SENSORS AND ELECTRONICS**

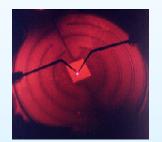
NASA GRC HAS VAST RANGE OF HIGH TEMPERATURE EXPERIENCE AND IS IN A POSITION TO PROVIDE NEEDED SOLUTIONS



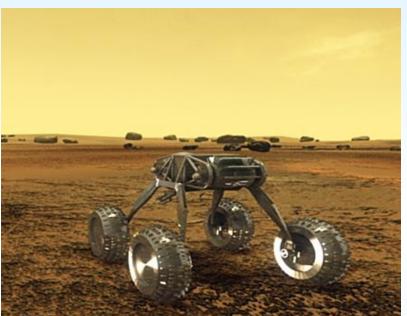


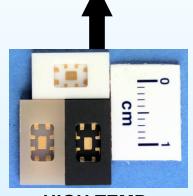
ELECTRONIC NOSE



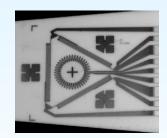


HIGH TEMPERATURE MICROELECTRONICS





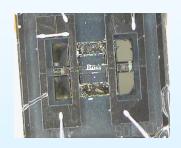
HIGH TEMP PACKAGING



MULTIFUNCTIONAL PHYSICAL SENSOR **ARRAY**



600°C PRESSURE SENSOR

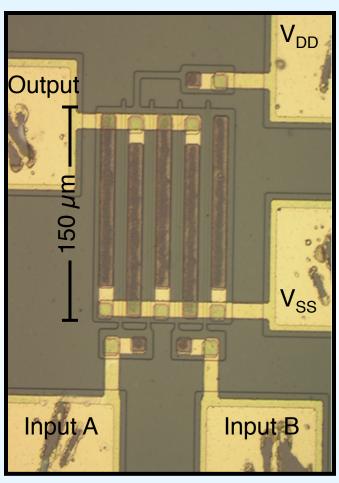


Hi-g SiC **ACCELEROMETER**

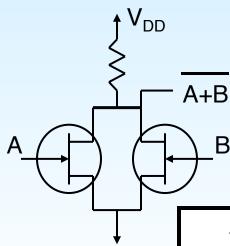


6H-SiC JFET NOR Gate

 $3 \times 300 \mu \text{m}$ JFET's



Unpackaged device tested for approx. 1 hour on prober with hot-chuck in 1997.

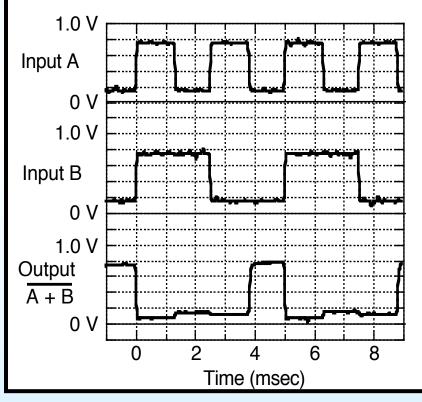


 V_{SS}

В

Α	В	A+B
0	0	1
0	1	0
1	0	0
1	1	0

 $\frac{T = 600 \text{ °C}}{V_{DD} = 3.5 \text{ V}}$ $V_{SS} = 0 V$ $V_{substrate} = -1.8 V.$





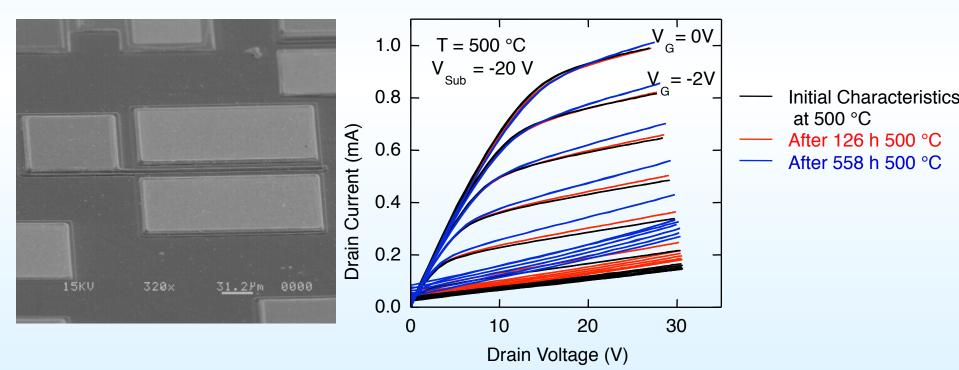
NASA/GMI 6H-SiC JFET Amplifier Circuit

(Under Construction) p epi SiC Substrate 52 15 235 micron



WORLD'S FIRST 500 HOUR 500 °C TRANSISTOR WITH VERY STABLE OPERATION

- 2000 hours of transistor operation achieved (some limited degradation)
- Device Operation Also Demonstrates Viability of Supporting Technologies
 - Packaging and ohmic contacts operated over 2000 hours at 500 °C without degradation.
- Strong Foundation for Improved Device Operation
 - > Revised "junction gate" process should enable 2000 hours at 500 °C without transistor degradation.



WORLD'S FIRST 500 C STABLE TRANSISTOR AND ITS PERFORMANCE OVER TIME



High Temperature Wireless Development

OBJECTIVES:

• HIGH TEMPERATURE WIRELESS TELEMETRY, DISTRIBUTED ELECTRONICS OVER A BROAD OPERATING RANGE

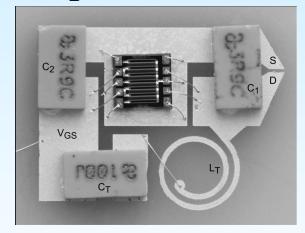
TECHNICAL CHALLENGES:

 DEVELOPMENT OF RELIABLE HIGH TEMPERATURE TELEMETRY ELECTRONICS, POWER SOURCES, REMOTE COMMUNICATION ELECTRONICS, AND PACKAGING

GOALS SUPPORTED:

- ENHANCE PERFORMANCE
- SIGNIFICANTLY REDUCE COST

PROVIDE DATA TRANSFER IN HARSH ENVIRONMENTS IMPROVING RELIABILITY AND ENABLING NEW CAPABILITIES



Prototype Oscillator Circuit

Example: Gas Turbine Engine Development Requires Extensive Instrumentation Yielding Extensive Wiring Complexity



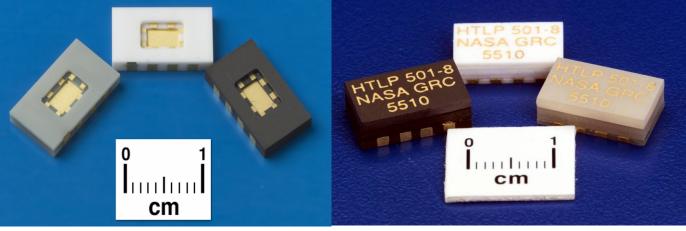
Wires from 1000 Sensors



Chip Level Packages for 500°C Application



96% Al₂O₃



90% Al₂O₃

- Three types of ceramic substrate and Au thick-film metallization based chip-level packages
- A compatible low resistance die-attach scheme tested for 1000hrs
- Compatible printed circuit board level interconnection system developed

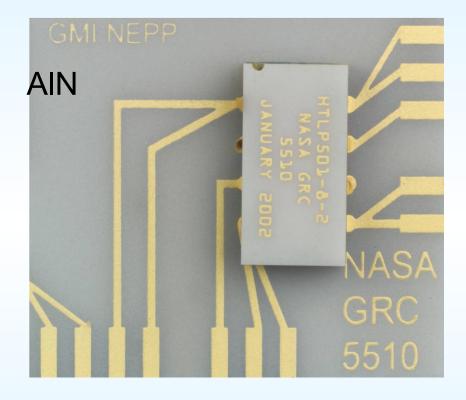


AIN

Circuit Board Level Interconnection



Electronic Package for High Temperature Micro-Systems



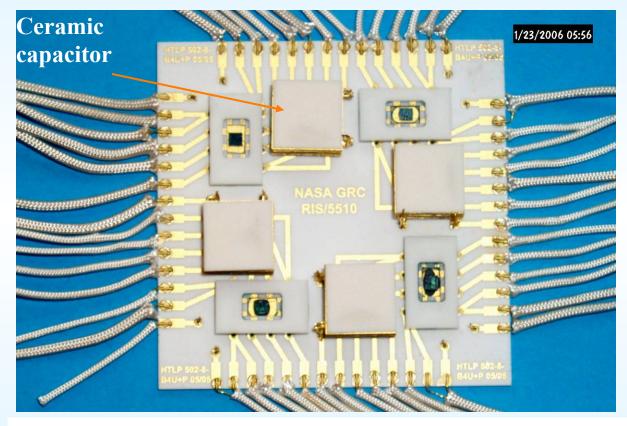
- Three types of ceramic substrate and Au thick-film metallization based PCB
- Interconnection between chip-level packages and PCB
- 500 C technology



Demonstration of 500°C AC Amplifier Based on SiC MESFET and Ceramic Packaging – Test assembly 2006



Optical Picture of the Test Assembly

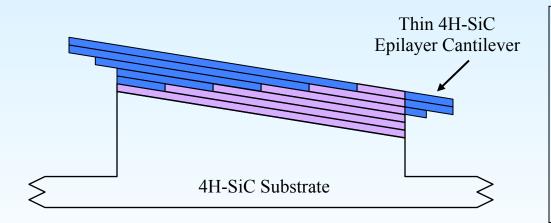


- The test assembly includes four testing circuit units
- Common Source AC amplifier tested at 500 C for over 1100 hours

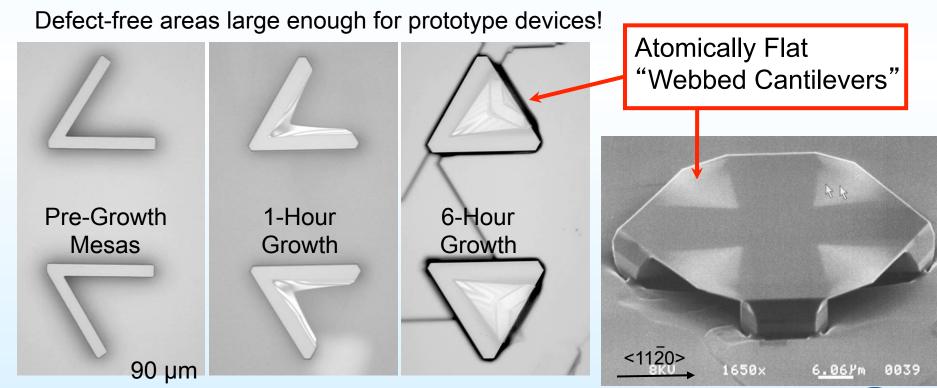


Atomically Flat SiC Mesas and Cantilevers

P. G. Neudeck et al., J. Appl. Phys. 92 p. 2391 (2002).



Top surface of mesa is atomically smooth completely free of steps.
Surface can be enlarged by growing defect-free cantilevers.

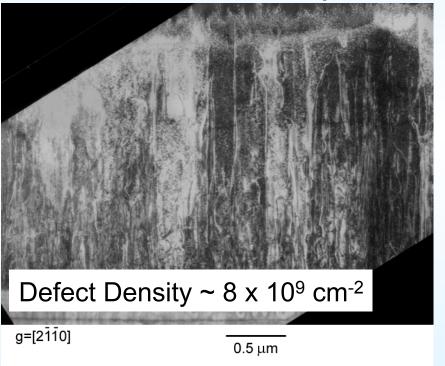


Accomplishment: Growth of Improved GaN on SiC Films

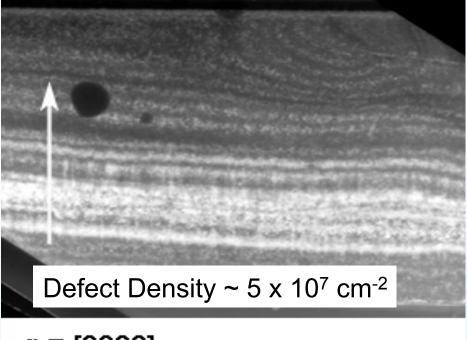
Method: Growth of GaN (by US Naval Research Laboratory) on top of Atomically Flat SiC Mesa Arrays Grown by NASA GRC.

Transmission Electron Micrographs (from NRL) Comparing GaN on SiC Films

GaN grown on top <u>of conventional</u>
<u>SiC with surface steps</u>



GaN grown on top of NASA GRC SiC mesa free of surface steps



$$g = [0002]$$
 $\frac{}{1 \mu m}$

GaN Dislocation Density Reduced by 100X!



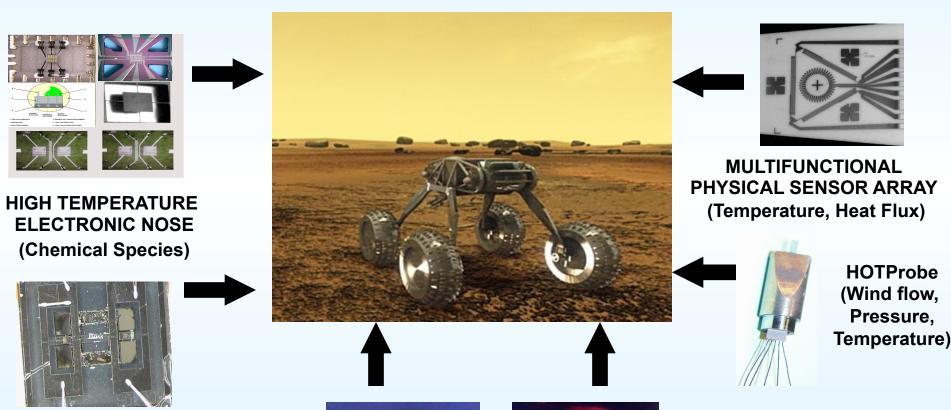
SUMMARY

NASA GRC HAS THE TOOLS TO ENABLE NEW MISSIONS

EXAMPLE POSSIBLE MISSION: Venus Integrated Weather Sensor (VIWS) System

Sensor Suite to Monitor Venus Weather Conditions including: Data Processing and

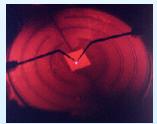
Communication, Wind Flow, Seismic, Pressure/Temperature/Heat Flux, Chemical Environment



Hi-g SiC ACCELEROMETER (Seismic Activities)

PRESSURE SENSOR (Pressure)





SiC ELECTRONICS (Data Processing and Com)



BACK UP SLIDES



NASA Glenn Microsystem Development Facilities

- Significant In-House Capabilities for a Range of Micro/Nano Sensor and Electronics Development
- Capabilities Range From Semiconductor Material and Device Fabrication to Packaging and Testing
- State-Of-The-Art Facilities Leading to World Leading Technologies

SiC Chemical Vapor
Deposition (CVD) Epitaxial
Growth Laboratory

Microsystems
Fabrication Clean
Room

Microdevices
Characterization Facilities



World's Most up-to-date Facility of Its Type



3000 Square Foot Clean Room Space for Electronic-Grade Oxides and MEMS



A Range of Characterization and Testing Equipment For Device Development



SiC-BASED PRESSURE SENSORS

- SIO HAS EXCELLENT MECHANICAL PROPERTIES FOR USE AS A HARSH ENVIRONMENT PRESSURE SENSOR (T > 500 °C, SILICON UNDERGOES PLASTIC DEFORMATION)
- FORM DIAPHRAM OF SiC AND INTEGRATE WITH ELECTRONICS
- WIDE RANGE OF APPLICATIONS

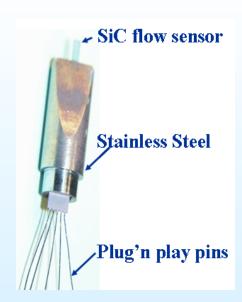
AERONAUTIC ENGINE APPLICATIONS
AUTOMOTIVE APPLICATIONS
MATERIAL PROCESSING

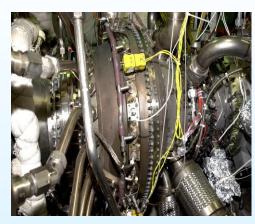
- ENGINE OPERATION DEMONSTRATED AT 500 C
- CAN BE INTEGRATED WITH FLOW VELOCITY AND TEMPERATURE FOR A VENUS HIGH TEMPERATURE WEATHER MONITORING DEVICE



500 °C SiC pressure sensor

SiC High Operating Temp. Probe (HOTProbe): SiC chip to simultaneously measure flow velocity, pressure, and temperature;

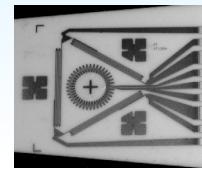




Real World Application: Pressure Sensor Installed in Engine Test

Thin Film Physical Sensors for High Temperature Applications

- Advantages for temperature, strain, heat flux, flow & pressure measurement:
 - Negligible mass & minimally intrusive (microns thick)
 - Applicable to all materials including ceramic based materials
 - Minimal structural disturbance
 - Intimate sensor to substrate contact & accurate placement
 - Multiple sensor fabrications, full-field measurement
 - High durability
 - Capable for operation to very high temperatures (> 1000°C)
- Multifunctional smart sensors being developed
- Can Be Used To Measure Venus Surface Conditions as well as Monitor Vehicle Conditions



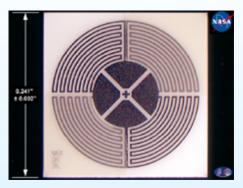
Multifunctional Sensor Array



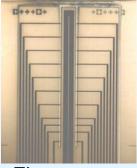
PdCr strain sensor On Alloy to T=1000°C



Pt- Pt/Rh temperature sensor to T=1200°C



Heat Flux Sensor Array to T=1000°C



Flow sensor to T=1000°C

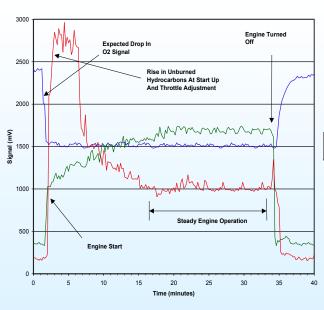


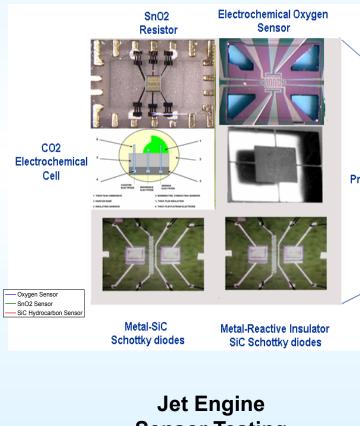
HIGH TEMPERATURE GAS SENSOR ARRAY HIGH TEMPERATURE ELECTRONIC NOSE



- High Temperature MEMS Based Gas Sensors Designed for Selective Detection
- Multiple Chemical Species Can Be Measured/Sensors Can Be Tailored for the **Application**
- Multiple Species of Interest To Venus Applications Can Be Detected

Automotive Engine Sensor Testing





Sensor Testing





